

PTO/SB/21 (08-90)
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Patent and Trademark Office: USA, DEPARTMENT OF COMMERCE

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TRANSMITTAL FORM (to be used for all correspondence after initial filling)			Application No.	09/47	09/475,104							
			Filing Date		December 30, 1999 2002							
			First Named Inventor	Nage	sh Vodrahalli L ROOM							
1			Group Art Unit	2823								
			Examiner Name	Deve	n M. Collins							
Total Number of Pages in This Submission 11			Attorney Docket Numbe	4239	42390P6785							
ENCLOSURES (check all that apply)												
Fee Transmittal Form		Assignmen (for an App	t Papers lication)		After Allowance Communication to Group							
Fee Attached		Drawing(s)			Appeal Communication to Board of Appeals and Interferences							
Amendment / Respon	se	Licensing-related Papers			Appeal Communication to Group (Appeal Notice, Brief, Reply Brief)							
After Final Affidavits/declaration(s)		Petition			Proprietary Information							
Extension of Time Request		Petition to Convert a Provisional Application			Status Letter							
Express Abandonment Request		Power of Attorney, Revocation Change of Correspondence Address			Other Enclosure(s) (please identify below):							
Information Disclosure Statement		Terminal Disclaimer										
Certified Copy of Priority Document(s)		Request for	Refund									
Response to Missing Parts/ Incomplete Application		CD, Numbe	r of CD(s)									
Response to Missing Parts under 37 CFR 1.52 or 1.53		Remarks										
					*							
SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT												
Firm William W. Schaal, Reg. No. 39,018												
Individual name BLAKELY, SOKOLOFF, PAYLOR & ZAFMAN LLP												
Signature Muy W												
Date Japuary 8, 2002												
CERTIFICATE OF MAILING/TRANSMISSION												
I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class mail with sufficient postage in an envelope addressed to: Box Non-Fee Amendment, Assistant Commissioner for Patents, Washington, D.C. 2023 on: January 8, 2002												
Typed or printed name Laura R. Robles												
Signature / Yau		a R	UNCO	Date	January 8, 2002							

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WIS PATENT OF COMMERCE

for FY 2000 Patent fees are subject to annual revision.	Filing Date First Named Inven		entor	Dece	ember 30, 1 esh Vodrah						
Applicant claims small entity status. See 37 CFR 1.27.	_	Examiner Name				vert M. Collins - 1100M					
		Group/Art Unit			2823						
TOTAL AMOUNT OF PAYMENT (\$) 0	.00	Attorney I	Docke	t No.	4239	0P6785					
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METHOD OF PAYMENT (check one)	 _	FEE CALCULATION (continued)									
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Deposit	12	7 50	227	25	Surcharge - late provi	stonal filing fee or					
Account Blakely, Sokoloff, Taylor & Zafman LLP	138	9 130	139	130	Non-English specifica	tion					
The Commissioner is authorized to: / check all that apply)	14		147	2,520	For filing a request for ex parte reexamination						
Charge fee(s) indicated below Credit any overpayments	111	2 920*	112	920 '	Requesting publication	n of SIR prior to					
Charge any additional fee(s) during the pendency of the application	71:	3 1,840*	113	1,840		n of SIR after					
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to the above-identified deposit account	111	5 110	215	55	Extension for reply wit	hin first month					
FEE CALCULATION	116	8 400	216	200	Extension for reply wit	hin second month					
BASIC FILING FEE	110	7 920	217	460	Extension for reply wit						
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Fee Fee Fee Fee Fee Paid Code (6) Code (5)	128		228	980	Extension for reply will	hin fifth month					
101 740 201 370 Utility filing fee	115		219	160	Notice of Appeal						
108 330 206 165 Design filing fee	120		220	160	Filing a brief in suppor						
107 510 207 255 Plant filing fee	121		221	140	Request for oral heart						
108 740 208 370 Reissue filing fee	140		138	1,510	Petition to institute a p Petition to revive - una		ng .				
114 160 214 60 Provisional filing fee	14:		241	640	Petition to revive - unr						
SUBTOTAL (1) (\$)	142		242	640	Utility issue fee (or rei						
2. EXTRA CLAIM FEES Extra Fee from		3 460	243	230	Design issue fee	,					
Claims below Fee Paid	144	620	244	310	Plant issue fee						
Total Claims 16 . 20" = 0 × 18.00 = \$0.00	123	2 130	122	130	Petitions to the Comm	issioner					
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102 84 202 42 Independent claims in excess of 3 104 280 204 140 Multiple Dependent claim, if not paid	l "	- 140	2.43	5,0	For each additional invention to be examined (37 GFR § 1.129(b))			1 1			
109 84 209 42 "Reissue independent claims over original	179	9 740	279	370	Request for Continues	Examination (RCE	E)				
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110 18 210 9 "Reissue claims in excess of 20 and over original patent	Other	fee (specify)		-							
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SUBMITTED BY			_		Comp	lete (if applic	able)				
Name (Print/Type) William W. Schaal		Registration No. (Attorney/Agent)			39,018						
Signature 01/08/02											
Signature Date 01/08/02 WARNING: Information on this form may become public. Credit card information should not											

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be included on this form. Provide credit card information and authorization on PTO-2039. Burden Hour Statement. This form is a spiralled for blake 0.2 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete fis form should be sent to re-Chef Information Officier. U.S. Platent and Trademark Office, Washington, DC 20231, DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS SEND TO. Assistant Commissions for Polerief. Washington, DC 20231



Docket No.:: 42390P678

In re Application of:

TO BELL MAIL ROOM

Vodrahalli, et al.

Examiner: Deven M. Collins

Application No.: 09/475,104

Art Group: 2823

Filed: December 30, 1999

For:

High Performance Thermal Interface Curing Process for Organic Flip Chip

Packages

AMENDMENT AND RESPONSE TO THE OFFICE ACTION

Assistant Commissioner for Patents Washington, DC 20231-9998

Sir:

In response to the outstanding Office Action, mailed December 20, 2001, please amend the above-identified Application as follows:

IN THE CLAIMS

Following is a complete set of claims as amended with this Response. This complete set of claims includes amended claims 6-8.

- A method for assembling an integrated circuit package, comprising: 5.
- applying an epoxy to an integrated circuit; 2
- placing a thermal element adjacent to the epoxy; and,
- curing the epoxy with energy at a microwave frequency.
 - (Amended) The method of claim 5, further comprising mounting the integrated circuit to a substrate.

042390.P6785 App. No. 09/475,104 -1-

WWS/irr Filed: 12/30/99